

1998 U.S. P.
16/081661
02/22/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10081661	FILING DATE 02/22/2002	CLASS 438	SUBCLASS 537	GAU 2812	EXAMINER Nguyen Ha
**APPLICANTS: Lee Soo-geun; Shin Hong-jae; Lee Kyoung-woo; Kim Jae-hak;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: REPUBLIC OF KOREA 01-25573 05/10/2001					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO SAM-0313	
TITLE : Method of manufacturing interconnection line in semiconductor device <small>U.S. DEPT. OF COMM./PAT. & TM.-PTO-436 (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Total Claims	Print Claim for O.G.
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Prepared for Issue	
		Application Examiner	
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